

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	9	(US-6209196-\$ or US-5722160-\$ or US-5629566-\$ or US-6133637-\$).did. or (JP-06164124-\$ or JP-04269893-\$ or JP-01072590-\$ or JP-57188833-\$).did. or (JP-2003224351-\$).did.	USPAT; JPO; DERWENT	OR	ON	2005/07/01 08:51
L2	1	1 and ((low adj meting\$3) or (high\$2 adj melting))	USPAT; JPO; DERWENT	OR	ON	2005/07/01 08:59
L3	303	(thermoplastic near (high\$2 adj melting))	USPAT; JPO; DERWENT	OR	ON	2005/07/01 08:54
L4	201	(thermoplastic adj resin) near (high\$2 adj melting)	USPAT; JPO; DERWENT	OR	ON	2005/07/01 08:54
L5	0	(anisotropic) near (high\$2 adj melting)	USPAT; JPO; DERWENT	OR	ON	2005/07/01 08:55
L6	0	(anisotropic) near (high\$2 adj melting)	USPAT; JPO; DERWENT	OR	ON	2005/07/01 08:55
L7	16	(anisotropic) near (melting adj point)	USPAT; JPO; DERWENT	OR	ON	2005/07/01 08:56
L8	1284	(solder) near (low adj melting adj point)	USPAT; JPO; DERWENT	OR	ON	2005/07/01 08:59
L9	0	7 and 8	USPAT; JPO; DERWENT	OR	ON	2005/07/01 08:56
L10	0	(solder) near (low adj melting adj point) near degree	USPAT; JPO; DERWENT	OR	ON	2005/07/01 08:59
L11	0	(solder) near (low\$2 adj melting adj point) near degree	USPAT; JPO; DERWENT	OR	ON	2005/07/01 08:59
L12	1747	(solder) near (low\$2 adj melting adj point)	USPAT; JPO; DERWENT	OR	ON	2005/07/01 08:59
L13	0	solder near ((low adj meting\$3) and (high\$2 adj melting))	USPAT; JPO; DERWENT	OR	ON	2005/07/01 09:00
L14	0	solder near ((low\$2 adj meting\$3) and (high\$2 adj melting))	USPAT; JPO; DERWENT	OR	ON	2005/07/01 09:01

L15	0	4 and 12	USPAT; JPO; DERWENT	OR	ON	2005/07/01 09:06
L16	6474	different with (melting adj point)	USPAT; JPO; DERWENT	OR	ON	2005/07/01 09:06
L17	64	16 and (mount\$3 with (electronic adj component))	USPAT; JPO; DERWENT	OR	ON	2005/07/01 09:51
L18	1974	174/259,260.ccls.	USPAT; JPO; DERWENT	OR	ON	2005/07/01 09:50
L19	227	18 and (mount\$3 with (electronic adj component))	USPAT; JPO; DERWENT	OR	ON	2005/07/01 09:51
L20	1	16 and 19	USPAT; JPO; DERWENT	OR	ON	2005/07/01 09:51
L21	14	18 and (mount\$3 with (electronic adj component) with support)	USPAT; JPO; DERWENT	OR	ON	2005/07/01 09:51
S1	6849	29/831,832,840,841,844,846,851,854.ccls.	USPAT; JPO; DERWENT	OR	ON	2005/06/30 16:43
S2	1747	156/64,356,357,358.ccls.	USPAT; JPO; DERWENT	OR	ON	2005/06/30 16:43
S3	1955	228/175,180,22,227.ccls.	USPAT; JPO; DERWENT	OR	ON	2005/06/30 16:43
S4	34921	mount\$3 with (electronic adj component)	USPAT; JPO; DERWENT	OR	ON	2005/07/01 09:07
S5	638	S1 and S4	USPAT; JPO; DERWENT	OR	ON	2005/06/30 16:44
S6	1648	melt\$3 near ((conduct\$3 adj bond\$3) or solder) with component	USPAT; JPO; DERWENT	OR	ON	2005/07/01 07:10
S7	67	S3 and S6	USPAT; JPO; DERWENT	OR	ON	2005/06/30 16:45
S8	0	S2 and S6	USPAT; JPO; DERWENT	OR	ON	2005/06/30 16:45
S9	3	S5 and S7	USPAT; JPO; DERWENT	OR	ON	2005/06/30 16:47

S10	96	S1 and S6	USPAT; JPO; DERWENT	OR	ON	2005/06/30 16:47
S11	38	S4 and S10	USPAT; JPO; DERWENT	OR	ON	2005/06/30 16:56
S12	4	(("5878942") or ("6133637")).PN.	USPAT; USOCR; JPO; DERWENT	OR	OFF	2005/06/30 16:56
S13	7	("4620215"   "4764804"   "5108950"   "5148266"   "5376825"   "5523628"   "5864178").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/30 16:56
S14	5	("4604644"   "5121190"   "5371404"   "5385869"   "5629566").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/30 16:58
S15	19	("5864178").URPN.	USPAT	OR	ON	2005/06/30 16:59
S16	7	("4620215"   "4764804"   "5108950"   "5148266"   "5376825"   "5523628"   "5864178").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/30 17:01
S17	7	("4620215"   "4764804"   "5108950"   "5148266"   "5376825"   "5523628"   "5864178").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/30 17:05
S18	20	TSUYOSHI-YAMAMOTO.in. or MITSUO-SUEHIRO.in. or HIROSHI-YAMADA.in.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/30 17:06
S19	0	S4 and S18	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/30 17:06
S20	0	S6 and S18	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/30 17:06
S21	3	melt\$3 near ((conduct\$3 adj bond\$3) or solder) with (before near mount\$3 with component)	USPAT; JPO; DERWENT	OR	ON	2005/06/30 17:07
S22	2	JP-01072590-.did.	USPAT; JPO; DERWENT	OR	ON	2005/07/01 07:02
S23	3	(melt\$3 or heat\$3) near (solder adj paste) with (terminal adj pad)	USPAT; JPO; DERWENT	OR	ON	2005/07/01 07:07
S24	2	(melt\$3 or heat\$3) same (solder adj paste) same (terminal adj pad) same (before or (prior adj to))	USPAT; JPO; DERWENT	OR	ON	2005/07/01 07:08

S25	28	melt\$3 near ((conduct\$3 adj bond\$3) or solder) with before with mount\$3	USPAT; JPO; DERWENT	OR	ON	2005/07/01 07:10
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Pao, Y.-H.;

Components, Hybrids, and Manufacturing Technology, IEEE Transactions on [see also Components, Packaging, and Manufacturing Technology, Part A, B, C]  
Volume 15, Issue 4, Aug. 1992 Page(s):559 - 570[AbstractPlus](#) | Full Text: [PDF\(884 KB\)](#) [IEEE JNL](#)**2. Solder paste printing process modelling map**

Ekere, N.N.; Mannan, S.H.; Currie, M.A.;

Electronic Manufacturing Technology Symposium, 1995, Proceedings of 1995 Japan Int'l IEEE/CPMT International

4-6 Dec. 1995 Page(s):137 - 141

[AbstractPlus](#) | Full Text: [PDF\(364 KB\)](#) [IEEE CNF](#)**3. One-part fast cure chipbonder epoxy adhesives for electronic applications**

Figovsky, O.; Sklyarsky, L.; Sklyarsky, O.;

Adhesive Joining and Coating Technology in Electronics Manufacturing, 2000. Proceedings of International Conference on  
18-21 June 2000 Page(s):107 - 109[AbstractPlus](#) | Full Text: [PDF\(180 KB\)](#) [IEEE CNF](#)**4. PC 3000-the new generation of Isotropic conductive adhesives**

Neumann-Rodekirch, J.; Hagedorn, H.-W.;

Polymers and Adhesives in Microelectronics and Photonics, 2001. First International Conference on

21-24 Oct. 2001 Page(s):70

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